

10-04-2000

Docket No.: DC4844

FORM PTO-1595 (Modified)
(Rev. 6-93)
OMB No. 0651-0011 (exp 4/94)
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P08/REV02



HEET

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

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Tab settings

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):
Yongjun Lee
Koji Nakanishi

Additional names(s) of conveying party(ies) Yes No

2. Name and address of receiving party(ies):

Name: **Dow Corning Asia, Ltd.**

Internal Address: **4th Floor AIG Building**

Street Address: **1-1-3, Marunouchi, Chiyoda-ku**
Tokyo 100-0005 Japan

City: _____ State: _____ ZIP: _____

Additional name(s) & address(es) attached? Yes No

3. Nature of conveyance:

Assignment Merger
 Security Agreement Change of Name
 Other _____

Execution Date: **July 3 & July 6, 2000**

4. Application number(s) or registration numbers(s):

If this document is being filed together with a new application, the execution date of the application is: **7/3/00, 7/6/00, 7/18/00, 7/19/00, 7/24/00**

A. Patent Application No.(s) _____ B. Patent No.(s) _____

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: **Dow Corning Corporation**

Internal Address: **Attn: Alexander Weitz**
Intellectual Property Dept. - Mail CO1232

Street Address: **2200 W. Salzburg Road**
P.O. Box 994

City: **Midland** State: **MI** ZIP: **48686**

6. Total number of applications and patents involved: **1**

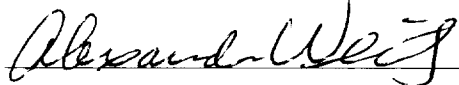
7. Total fee (37 CFR 3.41):.....\$ **40.00**

Enclosed - Any excess or insufficiency should be credited or debited to deposit account
 Authorized to be charged to deposit account

8. Deposit account number:
04-1520

10/03/2000 MTHAI1 00000200 041520 ALEXANDER WEIT DO NOT USE THIS SPACE

Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Alexander Weitz  **7/25/00**
Name of Person Signing Signature Date

Total number of pages including cover sheet, attachments, and document: **3**

PATENT

ASSIGNMENT

WHEREAS We, YONGJUN LEE and KOJI NAKANISHI

have invented certain new and useful improvements in

THERMOPLASTIC SILICONE ELASTOMERS FORMED FROM NYLON RESINS

for which application for United States Letters Patent has been executed by us on this 3 & 6 day of
July, 2000; and,

WHEREAS, DOW CORNING ASIA, LTD., 4th Floor, AIG Building, 1-1-3, Marunouchi, Chiyoda-ku, Tokyo 100-0005, JAPAN, is desirous of acquiring the said invention and said application and any and all Letters Patent that may be obtained therefor or thereupon, and all reissues and extensions thereof;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that for and in consideration of the sum of 250 Yen, and other good and valuable considerations, to us in hand paid by the said DOW CORNING ASIA LTD., the receipt of which is hereby acknowledged, we have sold, assigned, transferred and set over and by these presents do sell, assign, transfer and set over unto the said DOW CORNING ASIA LTD., its successors, and assigns, the full and exclusive right, title and interest in and to said invention and said application for Letters Patent of the United States therefor, and in and to any Divisions and Continuations thereof and in and to any and all United States Letters Patent and reissues and extensions thereof that may be issued for the said invention, to have and to hold for its own use and behoof and the use and behoof of its successors and assigns as fully and entirely as the same might be enjoyed by us if this sale and assignment had not been made; and

HEREBY AUTHORIZE and request the Commissioner of Patents and Trademarks to issue the said Letters Patent and any reissues and extensions thereof to the said DOW CORNING ASIA LTD. as assigns of the entire right, title and interest in and to the said invention and said application and Letters Patent issued therefor or thereupon; and

HEREBY AGREE to execute all instruments and documents within our power which may be necessary for the carrying out of this assignment in full; and to execute any divisional or continuing application or applications which may be necessary or proper to obtain full protection on the invention hereby assigned; and to execute any and all supplemental oaths and preliminary statements should the same be proper and necessary in the prosecution of the aforesaid applications; and

HEREBY FURTHER ASSIGN unto the said DOW CORNING ASIA LTD., its successors, and assigns, the whole right, title and interest in and to the invention disclosed in the said application throughout all

countries foreign to the United States, and do hereby ratify any acts of the said DOW CORNING ASIA LTD., its successors and assigns, in applying for patents therefor in its own name in countries where such procedure is proper and do agree to execute applications for said invention in the several countries where it is necessary that the same be executed by the inventors, and to execute assignments of such applications and the patents to be obtained therefor to the said DOW CORNING ASIA LTD. its successors and assigns.

IN WITNESS WHEREOF I have hereunto set my hand

Y. J. LEE

YONGJUN LEE

Dated: July 3, 2000

This is to certify that YONGJUN LEE has signed this document in my presence this _____ day of

July 3, 2000, Japan.

[Signature]
Signature of Witness

IN WITNESS WHEREOF I have hereunto set my hand

Koji Nakanishi

KOJI NAKANISHI

Dated: July 6, 2000

This is to certify that KOJI NAKANISHI has signed this document in my presence this _____ day of

July 6, 2000, Japan.

Achiro Murakami
Signature of Witness